

STPS60SM200C

Power Schottky rectifier

Features

- High reverse voltage (200 V)
- Low forward voltage drop
- High frequency operation

Description

The STPS60SM200C is a dual Schottky rectifier suited for high frequency switched-mode power supply.

Housed in TO-247, this device is especially suited for use in telecom base station SMPS, providing these applications with a good efficiency at both low and high load.

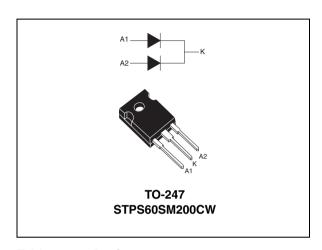


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	2 x 30 A
V _{RRM}	200 V
T _j (max)	175 °C
V _F (typ)	640 mV

Characteristics STPS60SM200C

1 Characteristics

Table 2. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit	
V_{RRM}	Repetitive peak reverse voltage	Repetitive peak reverse voltage			V	
I _{F(RMS)}	Forward current rms			50	Α	
1	Average forward current $\delta = 0.5$	Per diode, $\delta = 0.5$	T _c = 155 °C	30	Α	
I _{F(AV)}	Average lorward current $\delta = 0.5$	per device, $\delta = 0.5$	T _c = 150 °C	60		
I _{FSM}	Surge non repetitive forward current $t_p = 10$ ms sinusoidal, $T_c = 25$ °C			500	Α	
T _{stg}	Storage temperature range			-65 to + 175	°C	
Tj	Maximum operating junction temperature (1)			-40 to + 175	°C	

^{1.} $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter		Value	Unit
В	Junction to case	Per diode	0.7	
R _{th(j-c)}	Sunction to case	Total		°C/W
R _{th(c)}	Coupling		0.3	

When the two diodes 1 and 2 are used simultaneously: $\Delta T_i(\text{diode 1}) = P(\text{diode 1}) \times R_{th(i-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾ Reverse leaka	Povorco logizado gurrant	T _j = 25 °C	$V_R = V_{RRM}$			0.05	mA
'R`	I _R ⁽¹⁾ Reverse leakage current	T _j = 125 °C			6	13	
	$V_{F}^{(2)} \text{Forward voltage drop} \begin{array}{l} T_{j} = 25 ^{\circ}\text{C} \\ T_{j} = 125 ^{\circ}\text{C} \\ \hline T_{j} = 25 ^{\circ}\text{C} \\ \hline T_{j} = 25 ^{\circ}\text{C} \\ \hline T_{j} = 125 ^{\circ}\text{C} \\ \hline T_{j} = 25 ^{\circ}\text{C} \\ \hline T_{j} = 125 ^{\circ}\text{C} \\ \hline T_{j} = 125 ^{\circ}\text{C} \\ \hline \end{array} I_{F} = 30 \text{A} $		0.67	0.70			
		T _j = 125 °C	IF = 7.5 A		0.51	0.55	
V (2)		T _j = 25 °C	I _F = 15 A		0.73	0.77	V
v _E .,		T _j = 125 °C			0.57	0.61	V
		T _j = 25 °C	I - 20 A		0.79	0.83	
		T _j = 125 °C	1F = 30 A		0.64	0.69	

^{1.} Pulse test: $t_p = 5$ ms, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.58 \times I_{F(AV)} + 0.0037 \times I_{F}^{2}_{(RMS)}$$

^{2.} Pulse test: t_p = 380 μ s, δ < 2%

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Figure 1. Average forward power dissipation Figure 2. Average forward current versus awerage forward current ambient temperature (δ = 0.5) (per diode)

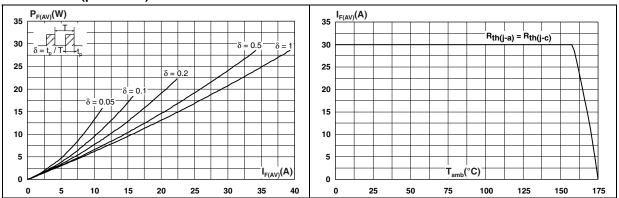


Figure 3. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

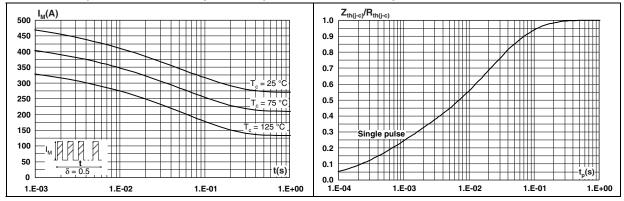
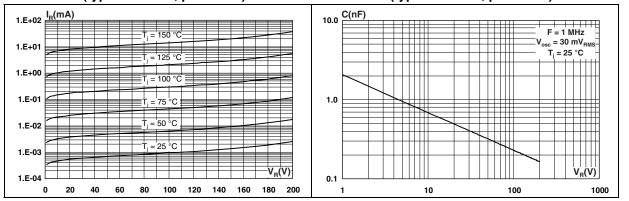


Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

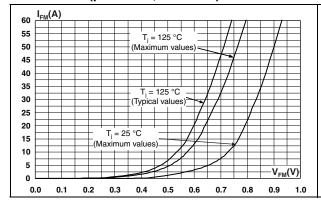
Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

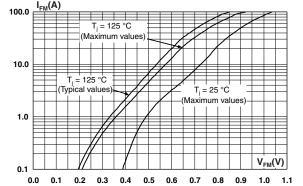


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Figure 7. Forward voltage drop versus forward current (per diode, low level)

Figure 8. Forward voltage drop versus forward current (per diode, high level)



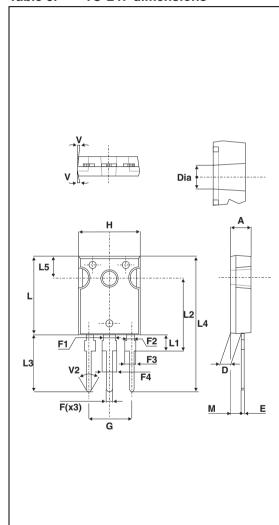


2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 to 1.0 N⋅m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 5. TO-247 dimensions



	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
Α	4.85	5.16	0.191	0.203	
D	2.20	2.60	0.086	0.102	
Е	0.40	0.80	0.015	0.031	
F	1.00	1.40	0.039	0.055	
F1	3.00	typ.	0.118	3 typ.	
F2	2.00	typ.	0.079 typ.		
F3	1.90	2.40	0.075	0.094	
F4	3.00	3.40	0.118	0.134	
G	10.90) typ.	0.429 typ.		
Н	15.45	16.03	0.608	0.631	
L	19.85	21.09	0.781	0.830	
L1	3.70	4.30	0.146	0.169	
L2	18.30	19.13	0.720	0.753	
L3	14.20	20.30	0.559	0.799	
L4	34.05	41.38	1.341	1.629	
L5	5.35	6.30	0.211	0.248	
М	2.00	3.00	0.079	0.118	
V	5° typ.		5° typ.		
V2	60° typ.		60° typ.		
Dia.	3.55	3.65	0.140	0.144	

Ordering information STPS60SM200C

3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS60SM200CW	STPS60SM200CW	TO-247	4.45 g	30	Tube

4 Revision history

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Table 7. Document revision history

Date	Revision	Changes
17-May-2011	1	First issue.

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